

**CoreFocus**  
**Report**  
**No.384**

GCMS

FID

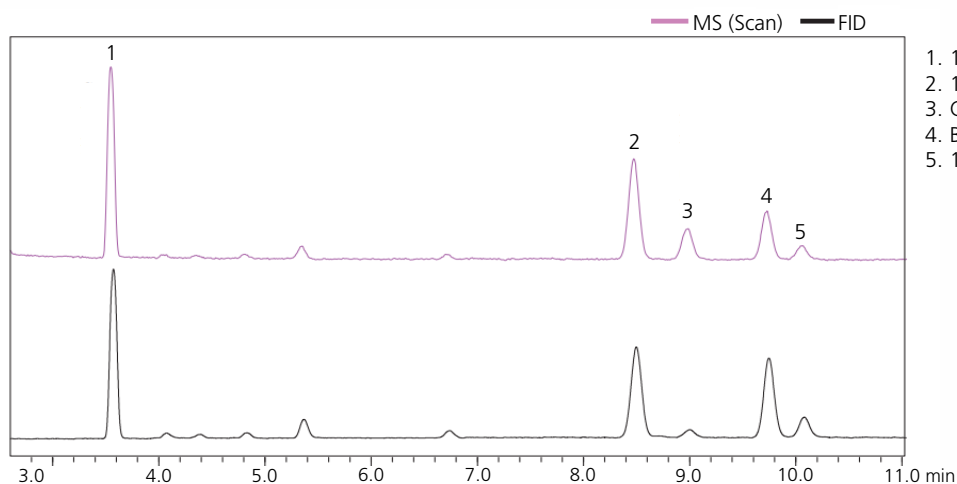
HS

SH Series

**SH-I-624Si MS**

**Analysis of Residual Solvents in Pharmaceuticals**

**Keywords: Headspace**



1. 1,1-Dichloroethene
2. 1,1,1-Trichloroethane
3. Carbon tetrachloride
4. Benzene
5. 1,2-Dichloroethane

Model : GCMS-QP™2020/HS-20/FID-2010 Plus  
Splitting System

**HS**

Mode : Loop (volume 1 mL)  
Oven temp. : 80 °C  
Sample line temp. : 90 °C  
Transfer line temp. : 105 °C  
Gas pressure : 76.4 kPa  
for vial pressurization  
Vial equilibrating time : 45 min  
Vial pressurizing time : 2.0 min  
Pressure equilibrating time : 0.1 min  
Load time : 0.5 min  
Load equilibrating time : 0.1 min  
Injection time : 0.5 min  
Needle flushing time : 15.0 min  
APC pressure : 20 kPa

**GC**

Column : SH-I-624Si MS (30 m x 0.32 mm I.D., 1.8 µm)  
P/N : 227-36077-01  
Injection mode : Split (Split ratio 1:5)  
Control mode : Constant pressure (89.4 kPa)  
Carrier gas : He  
Oven temp. : 40 °C (20 min) - 10 °C/min - 240 °C (20 min)  
Restrictor (FID) : 1.1 m x 0.25 mm  
Restrictor (MS) : 1.5 m x 0.20 mm  
APC pressure : 20 kPa

**FID**

Temp. : 250 °C  
Make-up flow rate : 30 mL/min (He)  
Hydrogen flow rate : 40 mL/min  
Air flow rate : 400 mL/min

**MS**

Ion source temp. : 200 °C  
Interface temp. : 250 °C  
SCAN range : *m/z* 29 to 250  
Event time : 0.3 s

Source : Application News M272 ([JP](#), [ENG](#))

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